



The PCOM-B703G, a Type 7 COM Express module, is designed with Intel® Xeon® processor D-2100 Skylake-D series. More specifically, based on the COM Express 3.0 specification's Type 7 pinout, when compared to the Type 6 pinout, trades all the graphics interfaces for four XGMII to support 10G ports, and more PCle lanes, makes the PCOM-B703 ideal for applications networking, micro server, switch, communication appliance, requiring power consumption while supporting high computing performance and communication throughput. The PCOM-B703 features four 10G management interfaces and two DDR4 DIMM sockets supporting up to 2667 MT/s and 128B ECC memory.

FEATURES

- Intel® Xeon® processor D-2100 NT series
- DIMM DDR4 2667 ECC up to128GB
- Support 4x USB3.0/2.0, 4x SATA III
- PCIe Gen 3 expansion (re-arrangeable for different combination of PCIe x16/ x8/ x4/ x2/ x1) up to 32 PCIe lanes
- Support High Speed Ethernet (4x XGMII/KR)

GENERAL

Form Factor Type 7, Extended Form Factor COM Express
Processor Intel® Xeon® processor D-2100 NT Skylake series
Memory Support up to 128GB DDR4 ECC up to 2667MHz DIMM
BIOS AMI Aptio V

Hardware Monitoring CPLD XO2 1200 / 2000
Storage Devices 2x SATA III 6.0Gb/s

I/O INTERFACE

Ethernet 4x XGMII / KR to support 4x 10G

PCIe Expansion 1x PCIe x16 Gen3
8x PCIe x1 Gen3
2x PCIe x4 Gen3
4x USB2.0
4 sets of SSRX/SSTX to support USB3.0

Connector COM Express Connector x2, supports both 8mm and 5mm design

Security TPM 1.2/2.0 (optional)

Others SPI, LPC, SMBUS, GPIO (8-bit, programable), I2C, UART x2

Mechanical & Environment

Dimension	155mm x 110mm (6.10" x 4.33")
Storage Temperature	-20°C ~ 70°C (-29°F~21°F)
Operating Temperature	0°C ~ 60°C (-32°F~140°F)
os	Microsoft Windows 7/8/8.1/10 Microsoft server 2012/2016 Linux Fedora 29/ Ubuntu 18.04/ CentOS 7
Power	+12V DC AT/ATX mode

*All information provided is subject to change without notice. Last updated: July, 2020